

ON Semiconductor			9/20/2020	
Base Part		NCP10672	HF	Pb-free
Orderable Part		NCP10672BD060R2G	Total weight (mg)	77.385
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	2.65	Silicon (Si)	7440-21-3	100
Die Attach	0.21	Silver (Ag)	7440-22-4	75
		Epoxy resins	129915-35-1	25
Lead Frame	27.35	Zinc (Zn)	7440-66-6	0.1
		Iron (Fe)	7439-89-6	2.3
		Copper (Cu)	7440-50-8	97.5
		Phosphorus (P)	7723-14-0	0.1
Mold Compound-Black	46.76	Epoxy resin	proprietary	7
		Phenolic Resin	proprietary	7
		Silica Amorphous (SiO ₂)	7631-86-9	15
		Carbon Black (C)	1333-86-4	0.5
		Fused Silica (SiO ₂)	60676-86-0	70.5
Plating	0.34	Palladium (Pd)	7440-05-3	6.22
		Nickel (Ni)	7440-02-0	92.71
		Gold (Au)	7440-57-5	1.07
Wire Bond - Cu	0.075	Copper (Cu)	7440-50-8	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of RoHS restricted substances. Lead (Pb) and lead oxide (PbO) are exempted with the RoHS exemption 7(a), 7(c) and 15. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>https://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				